

For Immediate Release



**Autosplice Solderball Pin Technology
Receives Top IPC Award
Presented at IPC Printed Circuits Expo**

San Diego, CA - - Autosplice's innovative Solderball Pin™ technology received the IPC's "Best Poster Technical Paper" award at the 50th Anniversary IPC Printed Circuits Expo, APEX show and Designer's Summit in Los Angeles, CA. The paper also received special recognition as the only award presented at the closing keynote ceremony on February 22, 2007. Carlos Juvera accepted the award on behalf of Autosplice from Denny McGuirk, IPC Global President.

According to co-author and presenter Carlos Juvera, "Over the past two years, we've been fortunate to be able to present in-depth white papers on Solderball Pin technology at technical seminars hosted by various industry conferences; IPC Technology Market Research Council (TRMC) Conference, Berlin Germany, SMTA International, Chicago IL, PAN Pacific Microelectronics Symposium, Honolulu, Hawaii and the Power Electronics Technology Conference in Long Beach CA. In addition, our product is being designed into several new OEM products to enhance power distribution, improve co-planarity, increase reliability and simplify assembly of stacked PCB board modules. The IPC Award is very gratifying because it further validates the technology from the perspective of the industry's foremost experts in real-world printed circuit applications."

Previously Autosplice Solderball Pin technology also received the "Best in Class" recognition in the components category at the Global SMT Technology Awards as part of the Assembly Technology Expo in Chicago in September 2006.

Solderball Pin technology employs a high performance conductive copper interconnect that incorporates a solder ball interface to the host PCB. The Solderball Pin provides two important attributes to PCB board module final assembly. The product provides additional solder and allows the sub-assembly to drop and align during the reflow process. These attributes contribute and compensate for PCB co-planarity variances up to .020" between board-to-board mezzanine stacking designs.

The inherent design flexibility of Solderball Pin technology allows designers of PCB-based modules the ability to determine the optimal pattern and positioning of individual interconnects, thereby maintaining design and layout consistency between new SMT versions and through-hole legacy versions, which provides a smooth transition for evolutionary surface mountable product revisions.

Solderball Pin technology is the preferred interconnection method in Point-of-Load power applications of OEM's such as Tyco Electronics, Texas Instruments and others.

Solderball Pin technology's compact configuration and flexibility as a discrete surface mount component have also facilitated its adoption into a broader scope of different applications, such as electronic lighting controls, remote telemetry monitoring, Ethernet, Fibre Channel, Storage Area Networks, Automotive, and many other daughter-to-motherboard module based sub-assemblies.

Autosplice is a global leader and manufacturer of interconnect components, assemblies and equipment, providing innovative automated solutions for the high-volume electronics industry.

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